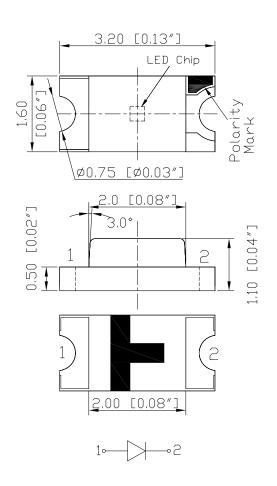
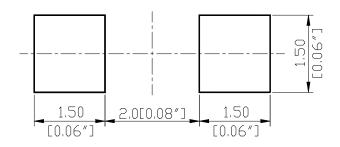


SPECIFICATION CS126AY2C-R

PACKAGE OUTLINES



RECOMMEND PAD LAYOUT



ITEM	MATERIALS		
Resin (mold)	Ероху		
Lens color	Water transparent		
Dice	AlGaInP/GaAs		
Emitted color	Yellow		

Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is \pm 0.25mm (0.01") unless otherwised noted.
- 3. Specifications are subject to change without notice.

Part Number Chip Material		Color of Emission	Lens Type	Viewing Angle
CS126AY2C-R	InGaAlP	Yellow	Water Clear	140°





ABSOLUTE MAXIMUM RATINGS

(TA=25°C)

Parameter	Symbol	Max Rating	Unit	
Forward Current	lF	30	mA	
Reverse Current @ 5V	lR	10	μΑ	
Power Dissipation	Pd	75	mW	
Operating Temperature Range	Тор	-40~+85	°C	
Storage Temperature Range	Тѕтс	-40~+85	°C	
Peak Pulsing Current (1/10 duty f = 10KHz)	lFP	125	mA	
Soldering Temperature	TsoL	Max 260°C for 5 sec Max		

OPTICAL-ELECTRICAL CHARACTERISTICS

(TA=25°C)

Parameter	Symbol	Test Condition	Value			Lloit
			Min	Тур	Max	Unit
Luminous Intensity	lv	IF = 20mA	40	65	125	mcd
Forward Voltage	VF	IF = 20mA	1.7	2.0	2.5	V
Reverse Leakage Current	lR	VR = 5V	-	-	10	μΑ
Viewing Angle at 50% Iv	201/2	IF = 20mA	-	140	-	Deg
Peak Wavelength	λР	IF = 20mA	-	595	-	nm
Dominant Wavelength	λD	IF = 20mA	585	590	595	nm

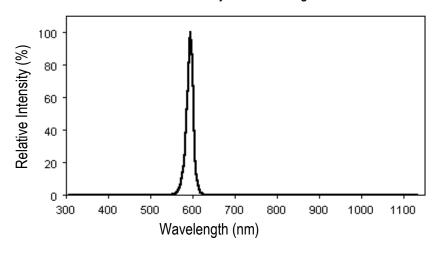
^{*}Tolerance of viewing angle: -10 / +5 deg.



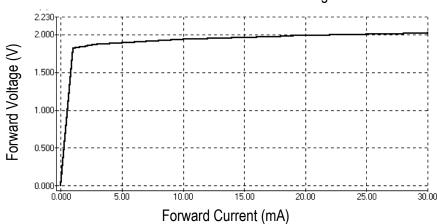


OPTICAL CHARACTERISTIC CURVES

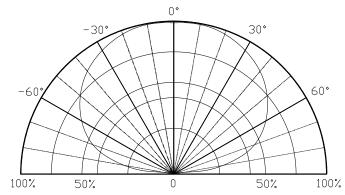
Relative Intensity vs. Wavelength



Forward Current vs. Forward Voltage



Directive Characteristics

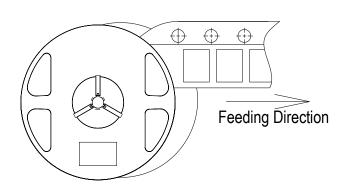


RoHS Compliant

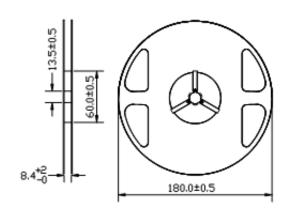


PACKAGING SPECIFICATION

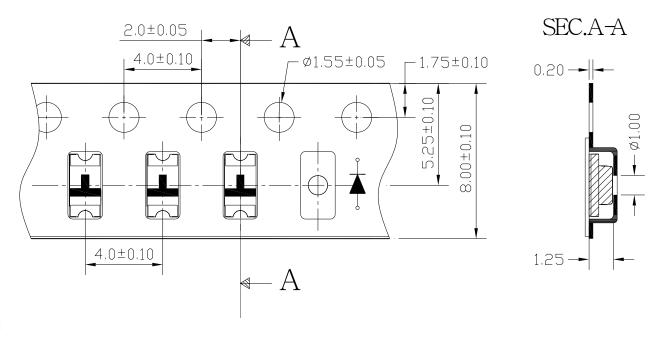
• Feeding Direction



Dimensions of Reel (Unit: mm)



Dimensions of Tape (Unit: mm)



Notes:

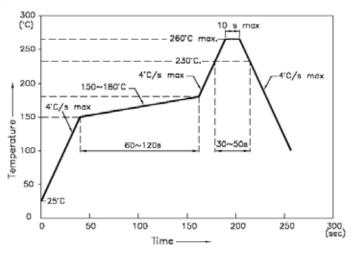
- 1. Empty component pockets are sealed with top cover tape;
- 2. The maximum number of missing lamps is two;
- 3. The cathode is oriented towards the tape sprocket hole.
- 4. 3,000pcs/Reel





SOLDERING CONDITIONS

REFLOW PROFILE



NOTES:

- 1. We recommend the reflow temperature 245°C (±5°C).the maximum soldering temperature should be limited to 260°C.
- 2. Do not cause stress to the epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process shall be 2 times or less.
 - Soldering iron
 - Basic spec is \leq 5sec when 260°C. If temperature is higher, time should be shorter
 - (+10°C → -1sec). Power dissipation of iron should be smaller than 20W, and temperatures should be controllable .Surface temperature of the device should be under 230°C.

Rework

- 1. Customer must finish rework within 5 sec under 260°C.
- 2. The head of iron cannot touch copper foil.
- 3. Twin-head type is preferred.

